

AI B  
could

1  
2  
3 A chip-scale package for an electronic device of the type  
4 having an acoustically active portion comprising:

5  
6 a die having an upper surface and having [at least one]  
7 the electronic device located at the upper surface of the die and  
8 having a plurality of signal connector pads located upon the upper  
9 surface of the die and having a bonding strip located upon the  
10 upper surface of the die,

11  
12 a lid made of a substantially non-conducting material and  
13 having a lower surface and an upper surface and having a lower  
14 surface bonding strip and a plurality of lower surface signal  
15 connector pads located upon the lower surface of the lid and  
16 having a plurality of upper surface signal connector pads located  
17 upon the upper surface of the lid, each upper surface signal  
18 connector pad being electrically connected to [a] one of the lower  
19 surface signal connector [pad] pads,

20  
21 directly each lower surface signal connector pad on the lid being  
22 electrically connected to [a] one of the signal connector [pad]  
23 pads located upon the upper surface of the die,

✓

24  
25 the bonding strip located upon the upper surface of the  
26 die being bonded by a bonding material to the bonding strip  
27 located upon the lower surface of the lid, the lid covering the  
28 electronic device but not being in physical contact with the